

REMARKS

Claims 1 and 7 are edited without narrowing or, therefore, Festo-like limitations, while the new gap limitation of claim 1 is supported by original Figs. 3, 4 and 5c and their descriptions in the specification.

The prior rejection of independent Claim 1 and, thus, the other dependent claims under 35 USC 103 (a) as obvious from the Applicant Admitted Prior Art (APA) has had to be now supported by further reliance on TW 451437, but even this combination of references does not disclose, teach or suggest all the features of Claim 1 whereas, for a rejection,

THE CLAIMED INVENTION AS A WHOLE MUST BE CONSIDERED *MPEP* 2141.02 I (emphasis original).

With regard to Claim 1, the Action finds the only difference between Claim 1 and APA is the obtuse angle θ between the positioning pin and the receiving part. This is traversed for the following reasons.

In APA, the first prior art reference of FIG. 1 disclosed a right angle or acute angle between the positioning pin 13 and the receiving part 12, and a plane of the positioning pin 13 is abutted against the entire side surface of the substrate 5. The second prior art reference of FIG. 2 disclosed an arched positioning pin 23. A plane of the positioning pin 23 facing the semiconductor encapsulant package is curved (not slant), and the plane of the positioning pin 23 is only abutted against a top edge of the side surface of the substrate 5. In comparison, in the amended Claim 1, taking FIG. 3 for example, the first plane of the positioning pin 331 is only abutted against a lower edge of the side surface of the substrate 5. Accordingly, the positioning pin 13 (FIG. 1) and the positioning pin 23 (FIG. 2) contact the encapsulant 7, whereas the positioning pin 331 (FIG. 3) does not contact the encapsulant 7.

With regard to TW 451437, the abutting portion of the mold 50 (FIGs. 2B and 2C) forms a blind hole to define a molding cavity for being fulfilled with an encapsulant. The abutting portion is a ring structure rather than a pin. After molding, the inner-wall of the abutting portion contacts the encapsulant. The obtuse angle of the abutting portion of the mold 50 is only a tapered angle for taking the package 60 out. In comparison, in the amended Claim 1, the positioning pin is used for positioning during dispensing process, and a gap is between the positioning pin 331 (FIG. 3) and the encapsulant 7. That is, the positioning pin 331 does not contact the encapsulant 7.

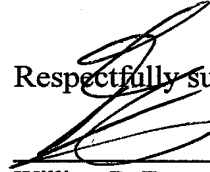
The obtuse angle in the amended Claim 1 can overcome the problems of glue leaking along the positioning pin to the backside of the substrate and the receiving part more effectively, whereby there is no rational underpinning for the combination of references, either.

... [R]ejections on obviousness cannot be sustained by mere conclusory statements; instead there must be some articulated reasoning with some rational underpinning to support the legal conclusion of obviousness. *Examination Guidelines for Determining Obviousness Under 35 U.S.C. 103 in View of the Supreme Court Decision in KSR International Co. v. Teleflex Inc.*, Fed. Reg. October 10, 2007, 57526, 57528-9.

Accordingly, the APA, TW 451437 and their combination do not disclose, teach and suggest all features of the amended Claim 1 and, in any event, should not be combined for the rejection of Claim 1 and, thereby, the other claims.

Reconsideration and allowance are, therefore, requested.

Respectfully submitted,

A handwritten signature in black ink, appearing to be 'W. Evans', written over a horizontal line.

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